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Semiconductor devices – Micro-electromechanical devices – Part 40: Test methods of micro-electromechanical inertial shock switch threshold

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**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –**

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inertial shock switch threshold**

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The text of this International Standard is based on the following documents:

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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 40: Test methods of micro-electromechanical inertial shock switch threshold

1 Scope

This part of IEC 62047 specifies the test conditions and methods of micro-electromechanical inertial shock switch threshold. This document applies to normally open micro-electromechanical inertial shock switch.

2 Normative references

There are no normative references in this document.